









# B2D20120H1

#### 1200V ▲ 20A ▲ SiC SCHOTTKY DIODE

SILICON CARBIDE SIC SCHOTTKY DIODE ▲ THT type

Excellent surge capability

Easy paralleling due to positive V<sub>F</sub> temperature coefficient

TO-247-2L package ▲ Epoxy meets UL94-V0

Temperature independent switching

Ultra-low forward voltage and high surge current

Item (T <sub>C</sub> = 25°C, unless otherwise noted)		Characteristics
Operating Temperature Range	T <sub>J</sub>	-55°C to +175°C
Storage Temperature Range	Ts	-55°C to +175°C
Repetitive Peak Reverse Voltage	$V_{RRM}$	1200V
Continuous Forward Current at T <sub>C</sub> = 160°C	I <sub>F</sub>	20A
Total Capacitive Charge (T <sub>J</sub> = 25°C)	$\mathbf{Q}_{c}$	120nC
Capacitance Stored Energy (V <sub>R</sub> = 800V)	Ec	62µJ
Diode Forward Voltage (T <sub>J</sub> = 175°C, I <sub>F</sub> = 20A)	$V_{F}$	1.78V
Power Dissipation	P <sub>TOT</sub>	366W

#### **APPLICATIONS**

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
<b>₹</b> /•			PFC	*		

#### **PIN DESCRIPTION**

Circuit Diagram	Outline • Front View	Pin No.	Description
Backside 0 1 2		1 2	Cathode (Backside) Anode

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## ABSOLUT MAXIMUM RATINGS ▲ T<sub>C</sub> = 25°C, unless otherwise noted

ltem	Condition	Symbol		Unit
Repetitive Peak Reverse Voltage		$V_{RRM}$	1200	V
Non-Repetitive Peak Reverse Voltage		$V_{RSM}$	1200	V
Continuous Forward Current	T <sub>C</sub> = 25°C	I <sub>F</sub>	77	Α
Continuous Forward Current	T <sub>C</sub> = 160°C	I <sub>F</sub>	20	Α
Non-Repetitive Forward Surge Current	$T_C$ = 25°C, $t_p$ = 10ms, Half Sine Wave	I <sub>FSM</sub>	190	Α
I <sup>2</sup> t Value	$T_C = 25^{\circ}C$ , $t_p = 10$ ms	∫i²dt	180.5	$A^2s$
Power Dissipation	T <sub>C</sub> = 25°C	P <sub>TOT</sub>	366	W
Power Dissipation	T <sub>C</sub> = 110°C	$P_{TOT}$	159	W
Operating Junction Temperature		$T_J$	-55 to +175	°C
Storage Temperature Range		$T_{STG}$	-55 to +175	°C
TO-247 Mounting Torque	M3 Screw		0.7	Nm

#### **ELECTRICAL CHARACTERISTICS**

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Static Characteristics						
DC Blocking Voltage	T <sub>J</sub> = 25°C	$V_{DC}$	1200			V
Diode Forward Voltage	$I_F = 20A, T_J = 25^{\circ}C$	$V_{F}$		1.35	1.60	V
Diode Forward Voltage	$I_F = 20A, T_J = 175^{\circ}C$	$V_{F}$		1.78	2.70	V
Reverse Current	$V_R = 1200V$ , $T_J = 25^{\circ}C$	$I_R$		20	160	μΑ
Reverse Current	$V_R = 1200V, T_J = 175^{\circ}C$	I <sub>R</sub>		40	400	μΑ
Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Dynamic Characteristics						
Dynamic Characteristics	$V_R = 800V$ , $T_J = 25$ °C					
Total Capacitive Charge	$V_{R} = 800V, T_{J} = 25^{\circ}C$ $Q_{C} = \int_{0}^{V_{R}} C(V) dV$	Qc		120		nC
		Q <sub>c</sub>		120 1342		nC pF
Total Capacitive Charge	$Q_C = \int_0^{V_R} C(V) dV$					
Total Capacitive Charge  Total Capacitance	$Q_C = \int_0^{V_R} C(V) dV$ $V_R = 1V, f = 1MHz, T_J = 25^{\circ}C$	С		1342		pF

#### THERMAL RESISTANCE PERFORMANCE

Item	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance, Junction to Case	$R_{\theta,JC}$		0.410		K/W



#### REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 1 • Typical Forward Characteristics I<sub>F</sub> vs. V<sub>F</sub>

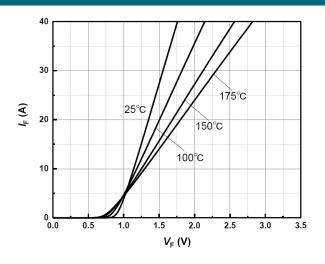


Fig. 2 • Typical Reverse Current I<sub>R</sub> as function of Reverse Voltage V<sub>R</sub>

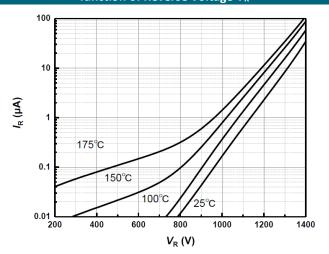


Fig. 3 • Diode Forward Current  $I_F$  as function of Case Temperature  $T_C$  (D = Duty Cycle)

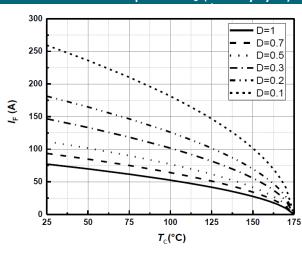


Fig. 4 • Typical Capacitance C as function of Reverse Voltage  $V_R$ ,  $C = f(V_R)$ ,  $T_J = 25^{\circ}C$ , f = 1MHz

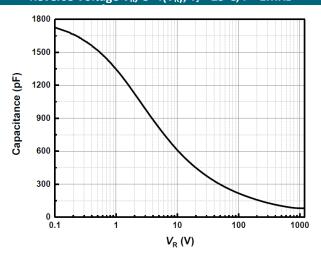


Fig. 5 • Typical Reverse Charge Q<sub>C</sub> as function of Reverse Voltage V<sub>R</sub>

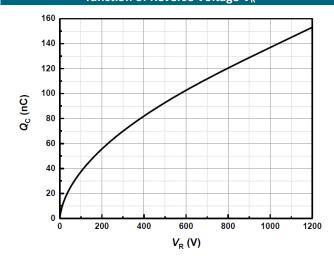
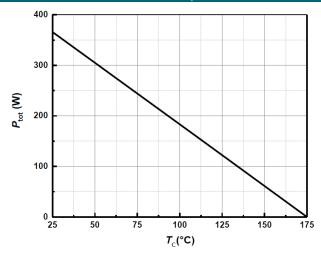


Fig. 6 • Power Dissipation  $P_{\text{TOT}}$  as function of Case Temperature  $T_c$ 



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#### REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 7 • Capacitance Stored Energy

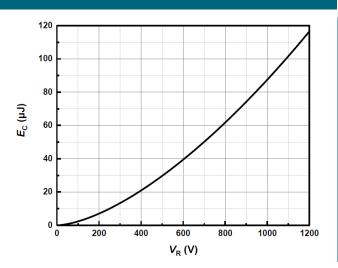
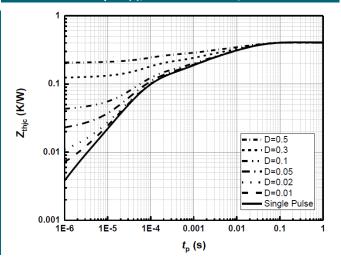
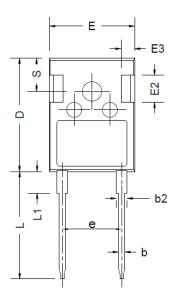


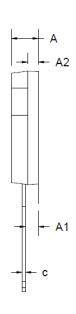
Fig. 8 • Maximum Transient Thermal Impedance, Z<sub>thjc</sub> = f(t), Parameter: D = t/T

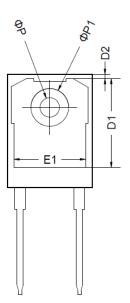




#### **PACKAGE OUTLINE**









Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
С	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
D2	1.05	1.17	1.35
E	15.50	15.80	16.10

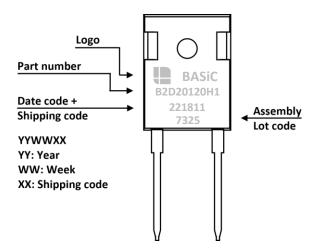
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e		10.88 BSC	
L	19.62	19.92	20.22
L1	-	-	4.30
ØΡ	3.40	3.60	3.80
ØP1	-	-	7.30
S		6.15 BSC	

#### **ORDERING INFORMATION**

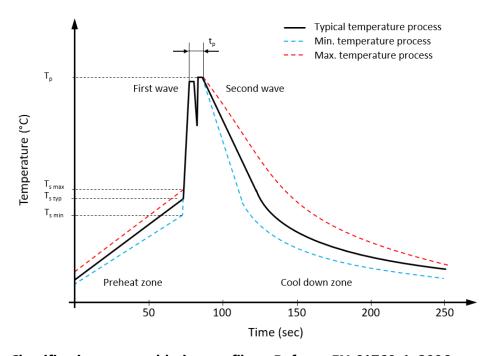
Part Nur	nber	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
B2D2012	0H1	TO-247-2L	Tube	30pcs	600pcs	3,000pcs



#### **PART MARKING**



### RECOMMENDED WAVE SOLDERING PROFILE & THT PACKAGE



#### Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{smin}$	100 °C	100 °C
Preheat temperature typical	T <sub>s typ</sub>	120 °C	120 °C
Preheat temperature max.	$T_{smax}$	130 °C	130 °C
Preheat time $t_s$ from $T_{smin}$ to $T_{smax}$	ts	70 seconds	70 seconds
Peak temperature	$T_p$	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	tp	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes

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#### **REVISION TABLE**

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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